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## **The OIF Starts 2010 With CEI and 100G Work**

### *Input from CEI Workshop Results in New 100G Project*

**Fremont, CA – February 11, 2010** – The Optical Internetworking Forum (OIF) is starting a new 100G project titled “VSR 28G Common Electrical Chip-to-Module Interface” which will support the use of less complex, lower power 100G optical modules. Feedback from attendees at the OIF’s Common Electrical Interface (CEI) workshop, held February 1, was that a very short reach chip-to-module electrical interface is needed to enable 100G optical modules that do not implement full retiming in the module.

“The OIF’s public workshop on CEI for 25G and 28G was a huge success,” said Rod Smith of Tyco Electronics and the OIF’s Market Awareness & Education Co-Chair. “More than 100 attendees, from both OIF member and non-member companies, came together to learn about the strategic initiatives within the OIF and to build on the relevant CEI work as the industry moves to 100G.”

The new project will result in an implementation agreement that will define data lane(s) that support bit rates up to 28 Gbps for chip-to-module interfaces with distances from zero to a minimum of 100 mm on a host PCB. The project will also define the channel model based on a chip-to-module application as well as define a test methodology for a chip-to-module interface including a single connector.

“This implementation agreement will allow lower power, smaller form factor multi-source 100G optical modules to be developed that will increase face-plate port density,” said David Stauffer, of IBM and the OIF’s Physical and Link Layer Working Group chair. “This will further the integration, power reduction and cost reduction of 100 Gbps line cards.”

Presentations at the CEI workshop were from the following companies: Broadcom, Brocade, Cisco Systems, Finisar, Force 10 Networks, IBM Corporation, LSI, Tyco Electronics, Xilinx.

In other news during the OIF’s first quarter meeting of 2010, David Stauffer was re-elected as the Chair of the Physical and Link Layer Working Group for a two-year term.

### **About the OIF**

Launched in 1998, the OIF is the first industry group to unite representatives from data and optical networking disciplines, including many of the world's leading carriers, component manufacturers and system vendors. The OIF promotes the development and deployment of interoperable networking solutions and services through the creation of Implementation Agreements (IAs) for optical, interconnect, network processing, component and networking systems technologies. The OIF actively supports and extends the work of standards bodies and industry forums with the goal of promoting worldwide compatibility of optical internetworking products. Information on the OIF can be found at <http://www.oiforum.com>.